

HAT2299WP

Silicon N Channel Power MOS FET
Power Switching

REJ03G1528-0100

Rev.1.00

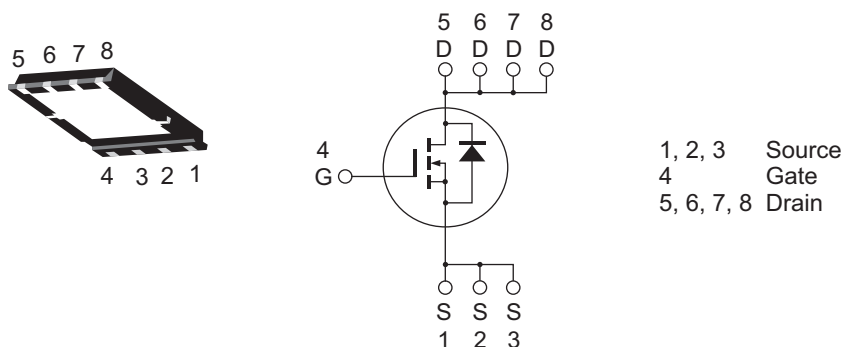
Mar 20, 2007

Features

- Low on-resistance
- Low drive current
- High density mounting

Outline

RENESAS Package code: PWSN0008DA-A
(Package name: WPAK)



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	150	V
Gate to source voltage	V_{GSS}	± 30	V
Drain current	I_D	14	A
Drain peak current	$I_{D(pulse)}$ ^{Note1}	28	A
Body-drain diode reverse drain current	I_{DR}	14	A
Body-drain diode reverse drain peak current	$I_{DR(pulse)}$ ^{Note1}	28	A
Avalanche current	I_{AP} ^{Note3}	14	A
Avalanche energy	E_{AR} ^{Note3}	14.7	mJ
Channel dissipation	P_{ch} ^{Note2}	25	W
Channel to case thermal impedance	θ_{ch-c}	5	°C/W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$

2. Value at $T_c = 25^\circ C$

3. $STch = 25^\circ C$, $T_{ch} \leq 150^\circ C$

Electrical Characteristics

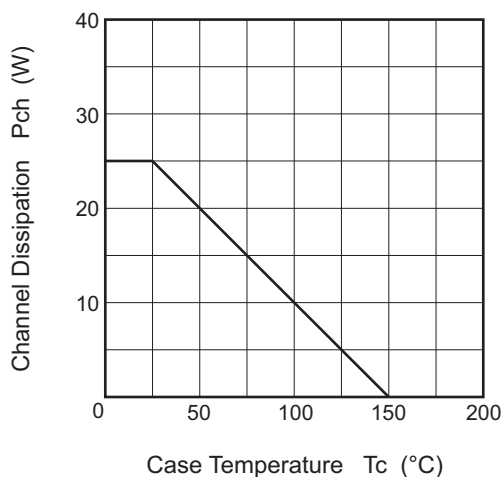
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	150	—	—	V	$I_D = 10 \text{ mA}$, $V_{GS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 150 \text{ V}$, $V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 0.1	μA	$V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	—	4.0	V	$V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$
Forward transfer admittance	$ y_{fs} $	6	10	—	S	$I_D = 7 \text{ A}$, $V_{DS} = 10 \text{ V}$ ^{Note4}
Static drain to source on state resistance	$R_{DS(on)}$	—	0.097	0.11	Ω	$I_D = 7 \text{ A}$, $V_{GS} = 10 \text{ V}$ ^{Note4}
Input capacitance	C_{iss}	—	710	—	pF	$V_{DS} = 25 \text{ V}$ $V_{GS} = 0$ $f = 1 \text{ MHz}$
Output capacitance	C_{oss}	—	160	—	pF	
Reverse transfer capacitance	C_{rss}	—	13	—	pF	
Turn-on delay time	$t_{d(on)}$	—	26	—	ns	$I_D = 7 \text{ A}$ $V_{GS} = 10 \text{ V}$ $R_L = 10.7 \Omega$ $R_g = 10 \Omega$
Rise time	t_r	—	31	—	ns	
Turn-off delay time	$t_{d(off)}$	—	53	—	ns	
Fall time	t_f	—	7	—	ns	
Total gate charge	Q_g	—	15	—	nC	$V_{DD} = 120 \text{ V}$ $V_{GS} = 10 \text{ V}$ $I_D = 14 \text{ A}$
Gate to source charge	Q_{gs}	—	4.3	—	nC	
Gate to drain charge	Q_{gd}	—	5.6	—	nC	
Body-drain diode forward voltage	V_{DF}	—	0.85	1.4	V	$I_F = 14 \text{ A}$, $V_{GS} = 0$ ^{Note4}
Body-drain diode reverse recovery time	t_{rr}	—	95	—	ns	$I_F = 14 \text{ A}$, $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

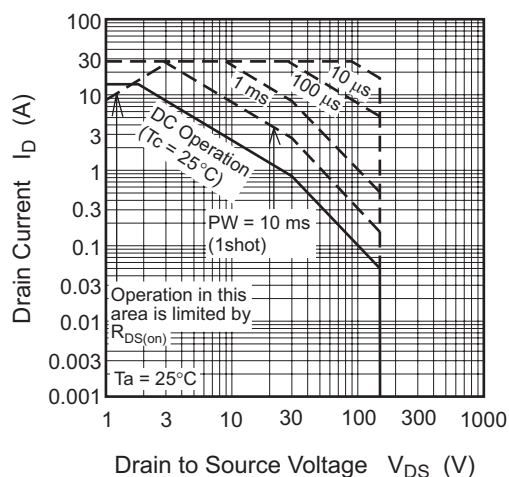
Notes: 4. Pulse test

Main Characteristics

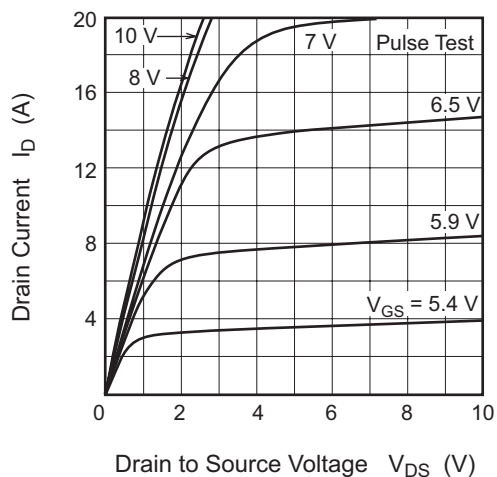
Power vs. Temperature Derating



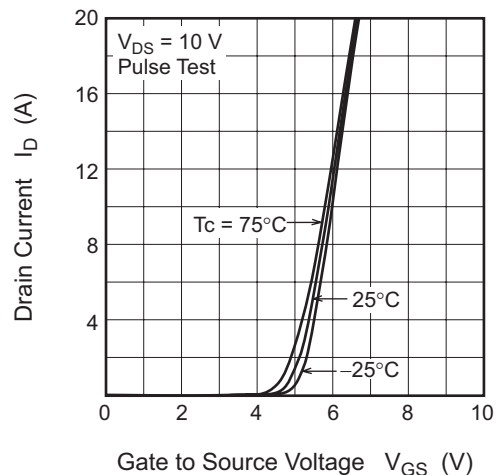
Maximum Safe Operation Area



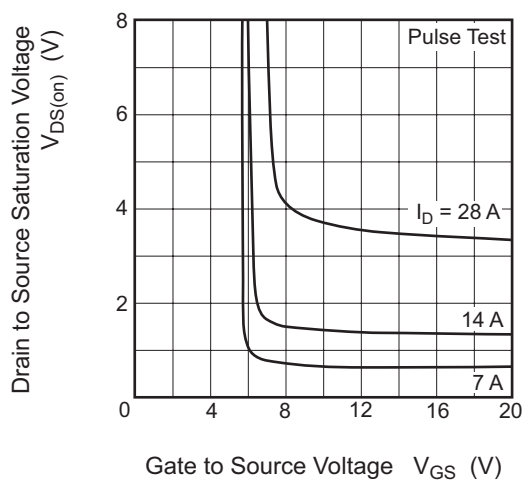
Typical Output Characteristics



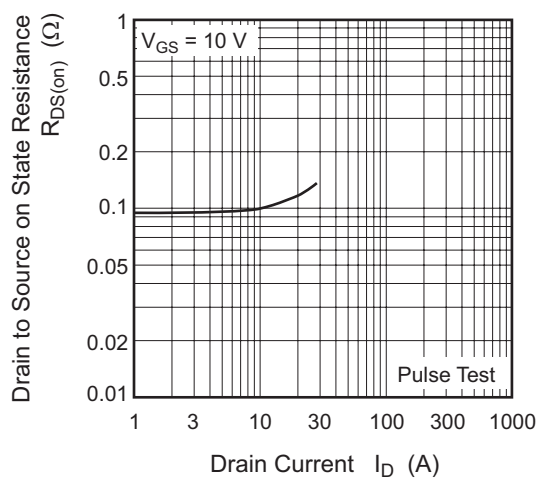
Typical Transfer Characteristics



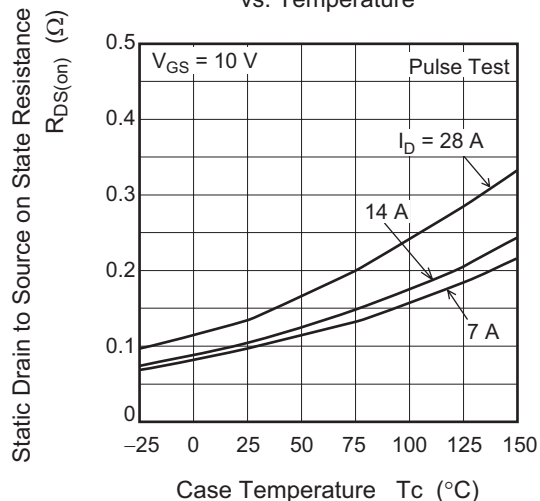
Drain to Source Saturation Voltage vs. Gate to Source Voltage



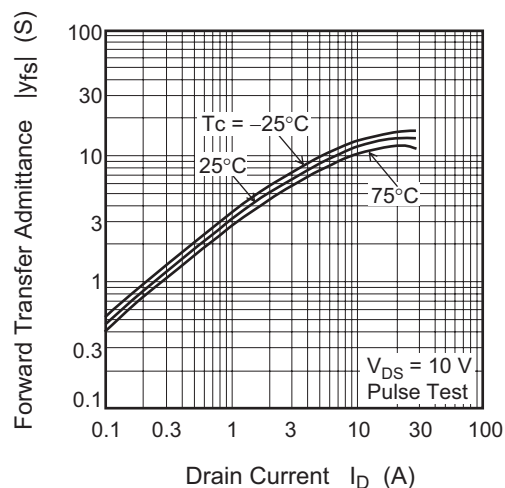
Static Drain to Source on State Resistance vs. Drain Current



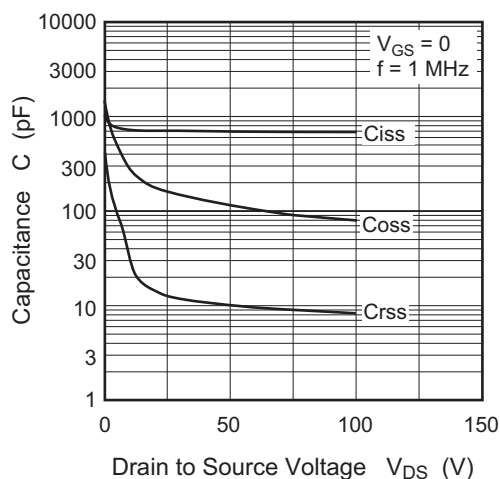
Static Drain to Source on State Resistance vs. Temperature



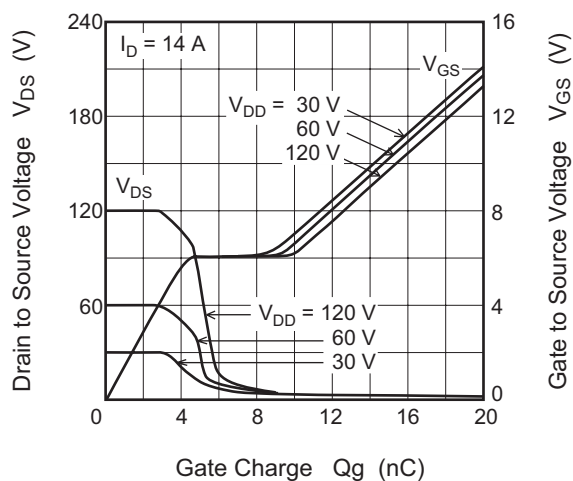
Forward Transfer Admittance vs. Drain Current



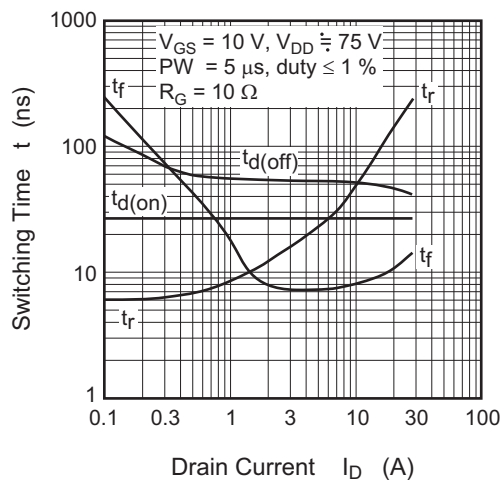
Typical Capacitance vs. Drain to Source Voltage



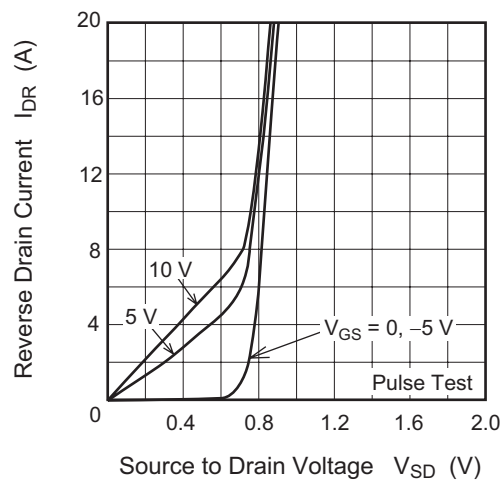
Dynamic Input Characteristics

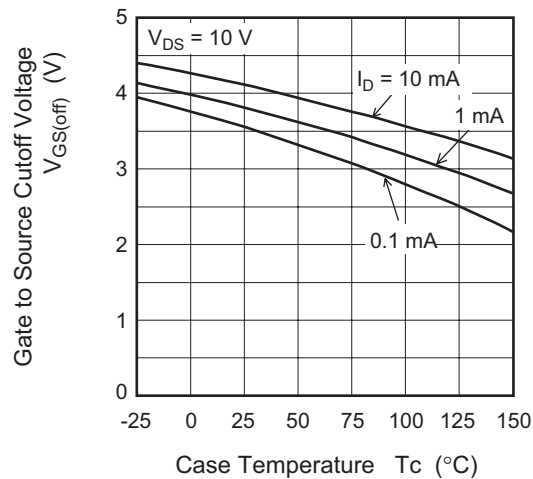


Switching Characteristics

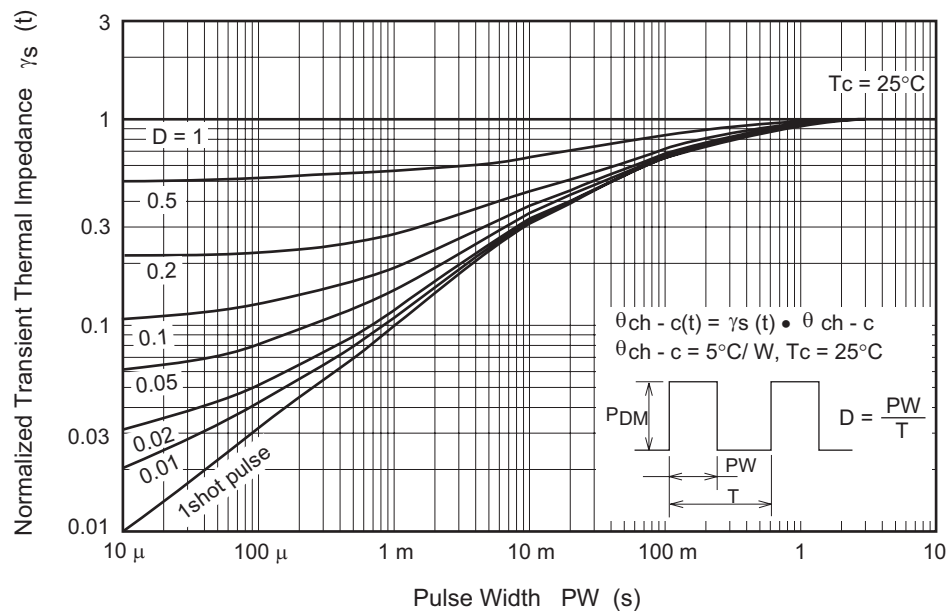


Reverse Drain Current vs. Source to Drain Voltage

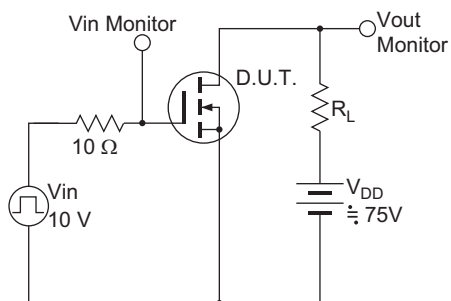


Gate to Source Cutoff Voltage
vs. Case Temperature

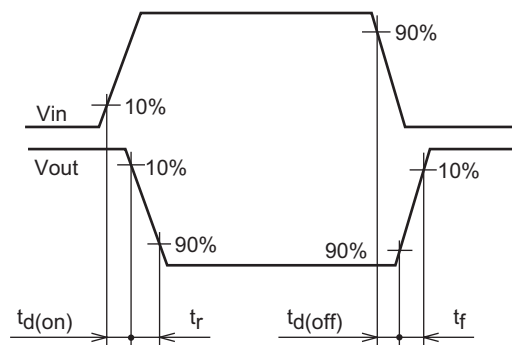
Normalized Transient Thermal Impedance vs. Pulse Width



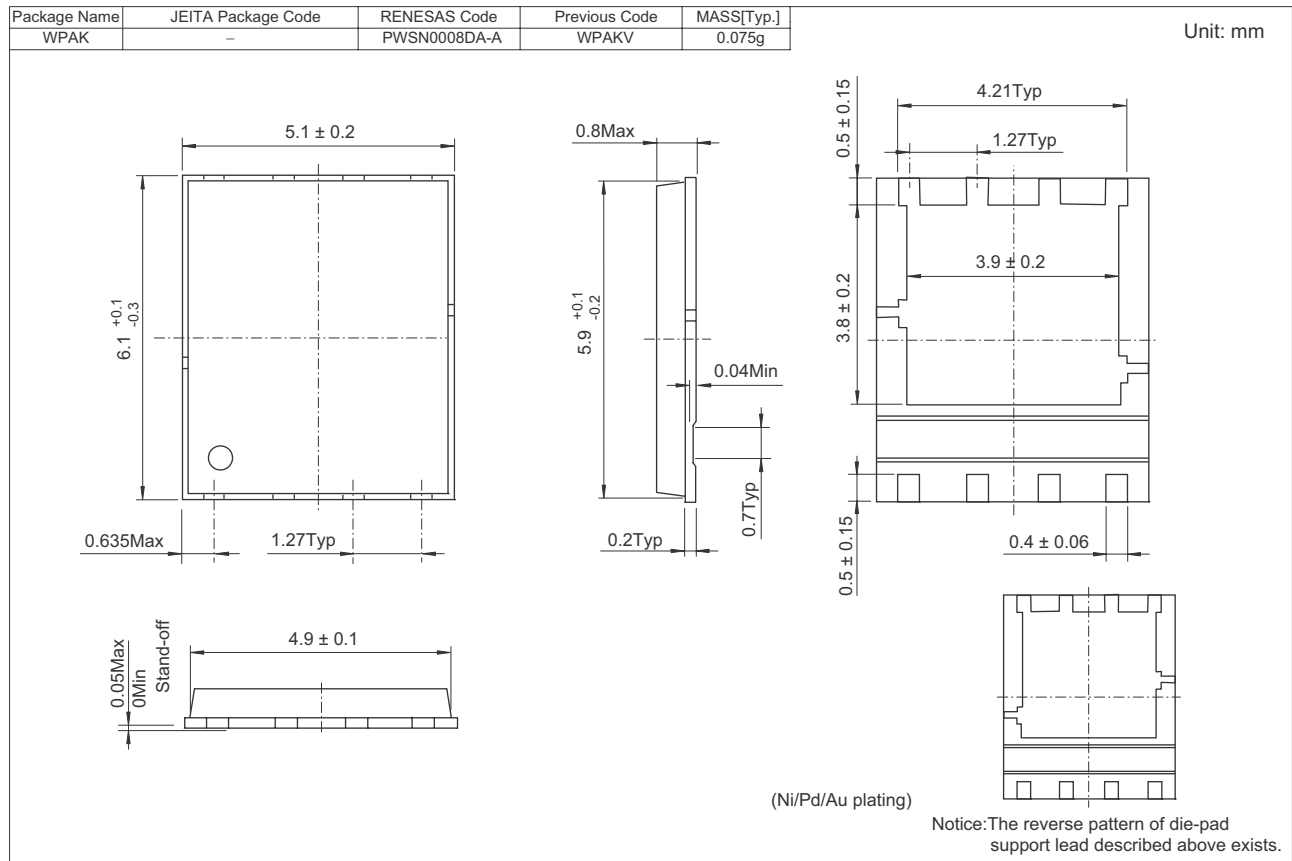
Switching Time Test Circuit



Waveform



Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2299WP-EL-E	2500 pcs	Taping

Notes:

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